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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Rodney C. Langley  
Serial No.: 09/438,692  
Filed: November 11, 1999  
Title: SEMICONDUCTOR DEVICE WITH IMPROVED BOND PADS

Examiner: Unknown  
Group Art Unit: 2811  
Attorney Docket No.: 3656US (95-0028-RE)

**POWER OF ATTORNEY BY ASSIGNEE  
AND CERTIFICATE UNDER 37 CFR § 3.73(b)**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

MICRON TECHNOLOGY, INC., assignee of the entire right, title and interest by assignment from the inventor(s) in the above-identified application, hereby appoints the following attorneys and agents:

David V. Trask, Reg. No. 22,012	William S. Britt, Reg. No. 20,969	Thomas J. Rossa, Reg. No. 26,799
Laurence B. Bond, Reg. No. 30,549	Joseph A. Walkowski, Reg. No. 28,765	James R. Duzan, Reg. No. 28,393
Allen C. Turner, Reg. No. 33,041	Kent S. Burningham, Reg. No. 30,453	Edgar R. Cataxinos, Reg. No. 39,931
Stephen R. Christian, Reg. No. 32,687	Brick G. Power, Reg. No. 38,581	Kenneth B. Ludwig, Reg. No. 42,814
Paul C. Oestreich, Reg. No. 44,983	Devin R. Jensen, Reg. No. 44,805	David L. Stott, Reg. No. 43,937
Kenneth C. Booth, Reg. No. 42,342	Samuel E. Webb, Reg. No. 44,394	Kerry D. Tweet, Reg. No. P-45,959
Eleanor V. Goodall, Reg. No. 35,162	Michael L. Lynch, Reg. No. 30,871	Lia M. Pappas, Reg. No. 34,095

as its attorneys with full power of substitution to prosecute this application and all applications claiming filing date priority therefrom and to transact all business in the U.S. Patent and Trademark Office in connection therewith.

**The above-identified assignee hereby elects, pursuant to 37 C.F.R. § 3.71, to conduct the prosecution of the above-identified patent application to the exclusion of the inventor(s).**

A chain of title from the inventor(s) of the above-identified patent application to the above-identified assignee is shown:

[X] In an assignment recorded in the U.S. Patent and Trademark Office at Reel 7807, Frame 0312.

[] In an assignment filed herewith for recordation, a true copy of which is attached hereto.

The undersigned has reviewed the above-identified assignment and, to the best of his knowledge and belief, title is in the above-identified assignee.

The undersigned further avers that he is empowered to make and sign the foregoing certification on behalf of the above-identified assignee, and to take the action set forth herein on its behalf.

Please direct all communications regarding the above-identified application to:

Joseph A. Walkowski,  
TRASK, BRITT & ROSSA  
P.O. Box 2550  
Salt Lake City, UT 84110  
Tele: (801) 532-1922  
Fax: (801) 531-9168

Respectfully Submitted,

MICRON TECHNOLOGY, INC.

Date: Jan 10, 2000

By: [Signature]  
Michael L. Lynch, Esq.  
Reg. No. 30,871  
Chief Patent Counsel,  
MICRON TECHNOLOGY, INC.

N:\2269\3656\Power of Attorney.wpd

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**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Reissue Application of:**

Rodney C. Langley

**U.S. Patent No.:** 5,686,762

**Issued:** November 11, 1997

**For:** SEMICONDUCTOR DEVICE WITH  
IMPROVED BOND PADS

**Reissue Serial No.:** 09/438,692

**Attorney Docket No.:** 3656US (95-0028-RE)

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

1/11/2000  
Date of Deposit

Lynette Eliason  
Signature of registered practitioner or other person having reasonable basis to expect mailing to occur on date of deposit shown pursuant to 37 C.F.R. § 1.8(a)(1)(ii)  
**Lynette Eliason**  
Typed/printed name of person whose signature is contained above

**ASSENT OF ASSIGNEE**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

The undersigned assignee of the entire interest in U.S. Patent No. 5,686,762 hereby assents to the accompanying application for reissue of U.S. Patent No. 5,686,762.


Pursuant to 37 C.F.R. §3.73, the undersigned representative of the Assignee has reviewed the evidentiary documents, specifically the Assignment to Micron Technology, Inc. recorded on December 21, 1995, at Reel 7807, Frames 0312-0314, and certifies that to the best of his knowledge and belief, title remains in the name of Micron Technology, Inc.

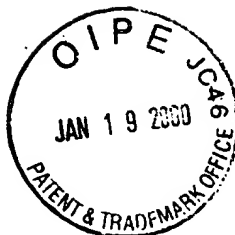
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The undersigned further avers that he is empowered to make and sign the foregoing certification on behalf of the Assignee, and to take the action set forth herein on behalf of the Assignee, pursuant to a resolution of its Board of Directors.

MICRON TECHNOLOGY, INC.

Dated: 1-10-2000

By:   
Michael L. Lynch  
Reg. 30,871  
Chief Patent Counsel



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Reissue Application of:**

Rodney C. Langley

**U.S. Patent No.:** 5,686,762

**Issued:** November 11, 1997

**For:** SEMICONDUCTOR DEVICE WITH  
IMPROVED BOND PADS

**Reissue Serial No.:** 09/438,692

**Attorney Docket No.:** 3656US (95-0028-RE)

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**1/11/2000**  
Date of Deposit

*Lynette Eliason*  
Signature of registered practitioner or other person having reasonable basis to expect mailing to occur on date of deposit shown pursuant to 37 C.F.R. § 1.8(a)(1)(ii)

**Lynette Eliason**

Typed/printed name of person whose signature is contained above

**OFFER TO SURRENDER**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

The undersigned applicant of the accompanying reissue application of Letters Patent for "SEMICONDUCTOR DEVICE WITH IMPROVED BOND PADS", U.S. Patent No. 5,686,762, granted November 11, 1997, of which Micron Technology, Inc. is now sole owner by assignment and on whose behalf and with whose assent the accompanying application is made, hereby offers to surrender said Letters Patent.

Pursuant to 37 C.F.R. § 3.73, the undersigned representative of the Assignee has reviewed the evidentiary documents, specifically the Assignment to Micron Technology, Inc. recorded on December 21, 1995, at Reel 7807, Frames 0312-0314, and certifies that to the best of his knowledge and belief, title remains in the name of Micron Technology, Inc.

The undersigned further avers that he is empowered to make and sign the foregoing certification on behalf of the Assignee, and to take the action set forth herein on behalf of the Assignee, pursuant to a resolution of its Board of Directors.

MICRON TECHNOLOGY, INC.

Date: Jun 10, 2000

By: 

Michael L. Lynch  
Reg. No. 30,871  
Chief Patent Counsel